Product Change Notification

112037 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**112037 - 00**
Change Title:	**Intel® 82801JO I/O Controller Hub (ICH10DO)** **Intel® 82801GB I/O Controller Hub (ICH7)** **Intel® 82801GR I/O Controller Hub (ICH7R)** **PCN 112037-00, Product Material**
Date of Publication:	**March 12, 2013**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Apr 24, 2013

Description of Change to the Customer:

The Intel® ICH7, ICH7R and ICH10 product wire bond material is changing from Gold (Au) to Copper Palladium (Cu-Pd).

Specifics of the change are:

- With recent advancements made in copper bonding, most of the assembly suppliers are switching to Cu-Pd as mainstream bonding process. Intel is following the High Volume Manufacturing (HVM) trend.
- Cu-Pd products are one-to-one pin compatible with Au products and there is no form, fit, function change.
- See "Products Affected/Intel Ordering Codes" table below for new product code, s-spec and MM#s.
- The products with the new marking have identical quality and reliability as the current products.

Customer Impact of Change and Recommended Action:

- Intel is moving with the rest of the industry per JEDEC standards.
- There are no changes to form, fit or function.
- The Cu-Pd and Au parts are totally compatible with each other.
- Customers do not need to do anything different in the receipt and use of the Cu-Pd products in their manufacturing process.
- Customers could get gold wire or copper palladium wire products until inventory is depleted.

Products Affected / Intel Ordering Codes:

Intel® I/O Controller Hubs						
	Pre Conversion			Post Conversion		
Marketing Name	**Product Code**	**S-Spec**	**MM#**	**Product Code**	**S-Spec**	**MM#**
Intel® 82801GR	NH82801GR S L8FY	S L8FY	870293	DW82801GR S LJZ9	S LJZ9	925748
Intel® 82801GB	NH82801GB S L8FX	S L8FX	870379	DW82801GB S LJZ8	S LJZ8	925747
Intel® 82801JO	AF82801JDO S LG8U	S LG8U	898943	DW82801JDO S LJZA	S LJZA	925883

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
March 12, 2013	00	Originally Published PCN